- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

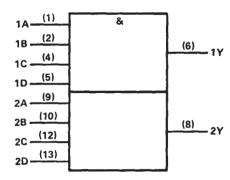
These devices contain two independent 4-input AND gates.

The SN54LS21 is characterized for operation over the full military temperature range of $-55\,^{\circ}\text{C}$ to 125 $\,^{\circ}\text{C}$. The SN74LS21 is characterized for operation from 0 $\,^{\circ}\text{C}$ to 70 $\,^{\circ}\text{C}$.

FUNCTION TABLE (each gate)

	INP	UTS		OUTPUT
A	В	С	D	Υ
Н	Н	Н	Н	Н
L	X	X	x	L
Χ	L	X	×	L
Х	X	L	X	L
X	Χ	Χ	L	L

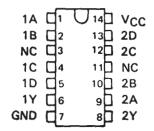
logic symbol†



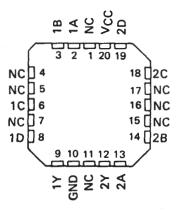
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

SN54LS21 . . . J OR W PACKAGE SN74LS21 . . . D OR N PACKAGE (TOP VIEW)

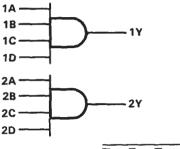


SN54LS21 . . . FK PACKAGE (TOP VIEW)



NC-No internal connection

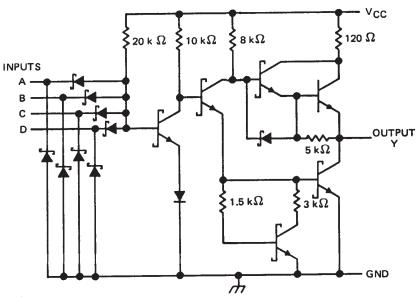
logic diagram



(positive logic) $Y = A \cdot B \cdot C \cdot D$ or $Y = \overline{A + B + C + D}$

SDLS139 - APRIL 1985 - REVISED MARCH 1988

schematics (each gate)



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Operating free-air temperature range: SN54'	
Storage temperature range	65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminals.



recommended operating conditions

			SN54LS	21		SN74LS	21	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	O.C.
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	٧
Іон	High-level output current			- 0.4			- 0.4	mA
loL	Low-level output current			4			8	mA
TA	Operating free-air temperature	- 55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEST CONDITIONS †				SN54LS	21		UNIT		
PARAMETER					TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = MIN,	I _I = - 18 mA				1.5			1.5	V
Voн	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OH} = - 0.4 mA	2.5	3.4		2.7	3.4		٧
	V _{CC} = MIN,	VIL = MAX,	I _{OL} = 4 mA		0.25	0.4		0.25	0.4	\ \ \
V _{CC} = MIN,		V _{IL} = MAX, I _{OL} = 8 mA						0.35	0.5	
l _l	V _{CC} = MAX,	V _I = 7 V				0.1			0.1	mA
Чн	V _{CC} = MAX,	V _I = 2.7 V				20			20	μА
Ι _Ι Ε	V _{CC} = MAX,	V ₁ = 0.4 V				- 0.4			- 0.4	mA
los§	V _{CC} = MAX			- 20		- 100	- 20		– 100	mA
Іссн	V _{CC} = MAX,	V ₁ = 4.5 V			1.2	2.4		1.2	2.4	mA
ICCL	V _{CC} = MAX,	V _I = 0 V			2.2	4.4		2.2	4.4	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDIT	TIONS	MIN	TYP	MAX	UNIT
tPLH .	_	.,	B -010	C. = 15 pE		8	15	ns
tPHL	Any	,	R _L = 2 kΩ,	C _L = 15 pF		10	20	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

 $[\]ddagger$ All typical values are at $V_{CC} = 5$ V, $T_A = 25^{\circ}$ C § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

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11-May-2023

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/31003B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31003B2A	Samples
JM38510/31003BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31003BCA	Samples
JM38510/31003BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31003BDA	Samples
M38510/31003B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31003B2A	Samples
M38510/31003BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31003BCA	Samples
M38510/31003BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31003BDA	Samples
SN54LS21J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS21J	Samples
SN74LS21DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS21	Samples
SN74LS21N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS21N	Samples
SN74LS21NE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS21N	Samples
SN74LS21NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS21	Samples
SNJ54LS21FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 21FK	Samples
SNJ54LS21J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS21J	Samples
SNJ54LS21W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS21W	Samples

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design. PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

PACKAGE OPTION ADDENDUM

www.ti.com 11-May-2023

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS21, SN74LS21:

Catalog: SN74LS21

Military: SN54LS21

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 12-May-2023

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

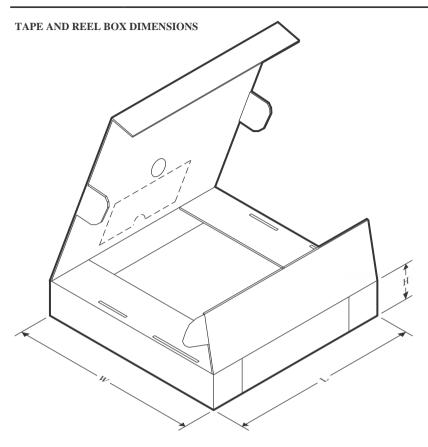


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS21DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS21NSR	so	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 12-May-2023



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS21DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74LS21NSR	SO	NS	14	2000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

www.ti.com 12-May-2023

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
JM38510/31003B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
JM38510/31003BDA	W	CFP	14	1	506.98	26.16	6220	NA
M38510/31003B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
M38510/31003BDA	W	CFP	14	1	506.98	26.16	6220	NA
SN74LS21N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS21N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS21NE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS21NE4	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54LS21FK	FK	LCCC	20	1	506.98	12.06	2030	NA
SNJ54LS21W	W	CFP	14	1	506.98	26.16	6220	NA

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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